Drwg. No. CU-120220-0161-K LOAD AT 1.45 MM HEIGHT INITIAL : 0.63 N (APPLYING LOAD) AFTER 3 x REFLOW : 0.60 N 3.57 MAX 0.6 -LOAD/DEFLECTION GRAPH (12) 2.18 MAX (27) 034 N/MM 0.5 MINIMUM CONTACT FORCES SHOWN CARRIER CUT TOLERANCE +0.25N / -0.0 N OFF POINT 0.4 INITIAL FORCE AT 2.15MM COMPRESSION FORCE 0.3 MONITORED BY SPC 0.2 (13) SCALE 10:1 -INITIAL FORCE AT 2.35MM COMPRESSION PICK & PLACE 0.39N (APPLYING LOAD) 0.32N (UNAPPLYING LOAD) Q.31N (APPLYING LOAD) 0.24N (UNAPPLYING LOAD) AFTER 3 x REFLOW : 0.28N (APPLYING LOAD) 0.10 D **AREA** (9) 0.1 AFTER 3 X REFLOW : 0.36N (APPLYING LOAD) 1.19 CONTACT POINT SELECTIVE 0.20N (UNAPPLYING LOAD) INITIAL FORCE ONLY TO BE MONITORED BY SPC TO BE ALIGNED RO.ES GOLD AREA 1.0 45 **€** 1/3 ·65. WITH C OF MICRONS MIN (10) SOLDER PAD COMPRESSION HEIGHT (MM)  $0.63 \pm 0.1$ FULLY COMPRESSED CONDITION (15) 0.1 A (8) 0.74 Min **OVER PICK &** At Max compression PLACE AREA. (2) 2.50±0.10 1.40±0.10 Α (3) 열 1) MINIMUM STROKE 1.0 MM. J WE SOL 2) SELECTIVE GOLD PLATE 2.1) FOR CONTACT FORCES SEE LOAD/DEFLECTION GRAPH. FORCE TO 60LD AREA 0.05/0.15 MICRONS BE MEASURED USING SPC AT COMPRESSED HEIGHT OF 2.15MM. 2.2) FOR CONTACT FORCES SEE LOAD/DEFLECTION GRAPH. FORCE TO (4) 3.38±0.20 0.98±0.10 BE MEASURED USING SPC AT COMPRESSED HEIGHT OF 2.35MM. (K) **(5)** 3) PLATING AFTER STAMPING 3.87 MAX. J 7 1.10 MAX III LOCAL AREA AROUND BENDS SELECTIVE GOLD BRUSH PLATING ON CONTACT POINT 1.0 MICRONS GOLD ZONE MINIMUM, AND OVER SOLDER PAD AREA 0.05/0.15 MICRONS OVER NICKEL UNDERLAYER 1.0/3.0 MICRONS. 4) MIN MATING CYCLES 100. 5) CONTACT RESISTANCE MAX 20 m $\Omega$ . 6) CRITICAL DIMENSIONS ARE RINGED. 7) UNSPECIFIED DIMENSIONS - LINEAR  $\pm 0.10$ , ANGULAR  $\pm 0.2^{\circ}$ . 8) NUMBERED BALOONS FOR CUSTOMER REFERENCE ONLY. SCALE 10:1 4.87±0.13 (6) 9) RECOMMENDED PCB PAD SIZE: 3.76 X 1.00 mm PDM: \*\*\* \*\*\* A3/B DO NOT SCALE Total Volume : 1.912 mm Total Surface Area : 35.014 mm Drawn Bills 01-APR-2008 Pro/E Generic Model MATERIAL:  $\oplus \subseteq$ Toupandun Industrial Area. Checked David 01-APR-2008 BERYLLIUM COPPER Jinda Cheng, Xiner Village, 3rd ANGLE RIE-2272, ADD NEW WORKING HEIGHT 2.35MM, 01-APR-2008 Engineer. Bills 01-APR-2008 0.125mm Shajing Town, Baoan District, UNIVERSAL CONTACT PROJECTION AND WIDTH TOLERANCE Shenzhen City 2.5MM Manufact. Surface Roughness PRC 518125 J RIE-1935 , ADD SOLDERING GOLD ZONE 26-FEB-2007 Cannon Electronics (SZ) Co. Ltd. Assembly Treatment: I RIE-1688, ADD PCB PAD SIZE IN THE NOTES. 10-May-06 Quality Unless Špecified | Ref: iss/rev CU-120220-0161

Cust Spec No:

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Scale 20:1

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Drwg.

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CU-120220-0161-K

2-4-10-08

H R1E-1604 Initial Issue

Iss Rev DCN/ECN or Description

23-Nov-05

Approvals Sign

Date

Dimensions in: mm

Cust Spec No:

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Scale 1:1

Sheet 2 of 2

2-4-10-08

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Dimensions in: mm